

Funding Opportunity – Facilities for Semiconductor Materials and Manufacturing Equipment

GUIDE: Instruction Guide for Full Application Forms and Narratives

Introduction

This document provides instructions and guidance for those filling out a Full Application as part of the CHIPS Incentive Program [Notice of Funding Opportunity for Facilities for Semiconductor Materials and Manufacturing Equipment](#) (Small-Scale Supplier NOFO). A Full Application is required for all applicants applying for semiconductor materials facilities and semiconductor manufacturing equipment facilities for which the capital investment falls below \$300 million. The CHIPS Program Office will extend due diligence phase invitations to applicants individually upon notifying them of their advancement.

The Full Application serves as an opportunity for applicants to fully explain how their proposed project addresses core program priorities. The Full Application includes a series of sections, each described below. Sections should be accompanied by relevant attachments that substantiate information in the narrative section. Each member of a consortium that seeks CHIPS Incentives for a project to construct, expand, or modernize a facility eligible for funding must submit a Full Application.

Please refer to the [Small-Scale Supplier NOFO](#) Section IV.H., [FAQs](#), [Fact Sheet](#), [Full Application Narrative Guidance](#), [Financial Model Template](#) and [Instructions](#), and other guidance materials on the CHIPS website, or email apply@chips.gov with additional questions.

Throughout the review process, the Department may request additional information and/or revisions regarding a Full Application submission.

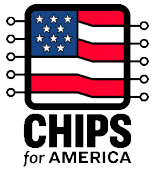


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1. Acknowledgement

Instructions: In the [web portal](#), you must complete the acknowledgement section of the Full Application before you can access the rest of the Full Application. By completing this section, you acknowledge that:

“Any communication, data, or other information stored or transmitted on this system may be accessed and used by federal employees, consultants, and contractors in accordance with Section IV.C. of the CHIPS Incentives Program – Facilities for Semiconductor Materials and Manufacturing Equipment (Small-Scale Supplier NOFO). By voluntarily furnishing information through this system, the applicant consents to such access and use.”

2. Cover Page and Applicant Profile

Instructions: Please populate all applicable and required fields to complete the Full Application cover page web form. Information that was submitted as part of the Concept Plan may already appear in the relevant fields. You have the option to directly update this information or leave it unchanged, provided that you review it and confirm its accuracy. This information includes:

- **Name of Application:** Provide a descriptive name for the application / project for which the entity is requesting CHIPS incentive funds.

Applicant Organization Information

Please enter the following information for the entity applying for CHIPS Incentives.

- **Applicant Name (e.g. applying entity):** Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application. Under the Small-Scale Supplier NOFO, an applicant may be a foreign entity.
- **Corporate Parent Name (if applicable):** Provide the legal name of the corporate parent of the entity applying for CHIPS Incentives. This could be the same name as the Applicant in some cases.
- **Mailing Address:** Include the street address, city, state, and zip code for U.S. addresses and equivalent information for foreign addresses, including country/location. If you do not know the 9-digit zip code for your U.S. location, enter “0000” for the last four digits.
- **Organization Website:** Provide a URL address for the applying entity’s website (or corporate parent if entity does not have a website).
- **Have you registered for a SAM.gov account?** Choose “Yes” or “No” from the dropdown menu to indicate whether the potential applicant has applied for an account in the federal government’s System for Award Management (SAM.gov). A prerequisite for any award by the Department is an active registration in the System for Awards Management (SAM). Potential applicants are strongly encouraged to begin the process of registering for SAM.gov as early as possible. While this process ordinarily takes between three days and two weeks, in some circumstances it can take six or more months to complete due to information verification requirements. CPO is unable to issue a CHIPS Incentive to an entity that lacks an active SAM.gov registration.
- **UEI # (Optional):** Provide your organization’s Unique Entity Identifier number in the field provided.

Applicant Point of Contact

Please enter the following information for the applicant point of contact, who should be an individual authorized to submit an application on behalf of the entity.

- **First Name:** The first name of the point of contact.
- **Last Name:** The last name of the point of contact.
- **Title:** The official title of the point of contact at the applying entity.
- **Phone Number:** A business phone number to reach the point of contact.
- **Email Address:** A business email for the point of contact associated with the applicant.

Additional Applicant Details

Please enter any additional information regarding the applicant.

- **Please list all primary officers (First Name, Last Name, Title):** The full name and title of every primary officer in the entity.
- **Is the global headquarters address the same as the organization address?:** Choose “Yes” or “No” from the dropdown menu to indicate whether the headquarters of the organization are located at the same organization address.
 - **Global Headquarters Address:** If you chose “No” in the previous question, please include the street address, city, state, and zip for US addresses and equivalent information for foreign addresses, including country/location. If you do not know the 9-digit zip code for your U.S. location, enter “0000” for the last four digits.
- **Select the applicant organization ownership structure:** Choose “Public” or “Private” from the dropdown menu to indicate how your organization’s ownership is structured.
- **List all major shareholders (if none, then write “N/A”):** Provide the legal name(s) of any entity/shareholder that owns >5% of equity in the applicant’s ownership structure. If no shareholder(s) holds more than 5% of equity, then write “N/A”.
- **List all countries of operations:** Provide a list of all countries in which the applicant operates.

Attestation

You must complete this attestation section of the Full Application before you can access the rest of the Full Application. By completing this section, you acknowledge that:

“Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.”

3. Sources and Uses of Funds

Instructions: In the [web portal](#), complete the summarized project sources and uses on a best-efforts basis. The figures provided in this web form are expected to be estimates and may be rough approximations for high-level cost categories. Information that was submitted as part of the Concept Plan may already appear in the relevant fields. You have the option to directly update this information or leave it unchanged, provided that you review it and confirm its accuracy.

Please also refer to Section IV.H.8 of the [Small-Scale Supplier NOFO](#) for an overview of the requirements for this portion of the Full Application.

3i. Uses of Funds Form

Instructions: Complete the fields under the Schedule A: Summation Across Projects – Cost Schedule (\$ USD) section under the Use of Funds Form with cost estimates.

Note, total capital investment must fall below \$300 million. Full Applications determined to be ineligible, incomplete, or nonresponsive will be rejected. Potential applicants should enter “0” for any costs that are not applicable to their project.

Schedule A: Summation Across Projects – Cost Schedule (\$ USD)

Please enter the amounts for the following categories (units should not be in Thousands or Millions).

1. **Capital Investment:** Costs required to complete construction of the facility and initiate operations. Note, this field will automatically sum the fields 1a – 1f below.
 - a. **Land:** Enter the amount of costs which may include, but is not limited to, land acquisition, site restoration, land improvements, cost of appraisal, right-of-way acquisitions, relocation expenses and payments, demolition and removal costs, or other costs associated with land.
 - b. **Construction Costs (Labor, Materials):** Enter the amount of costs which may include, but is not limited to, labor, material, and other costs associated with construction of the facility. Any costs to build the clean room should be included within construction.
 - c. **Equipment:** Enter the amount of costs which may include, but is not limited to, initial equipment purchases or modernization costs, installation expenses, spare parts, and other equipment-related costs.
 - d. **Infrastructure Improvements (Utility Plants, Access to Infrastructure, Wastewater Treatment):** Enter the amount of costs which may include, but is not limited to, the construction or improvement of utility plants required for the facility; costs associated with gaining access to infrastructure such as roads, water, power etc.; wastewater treatment plants; fencing; and other infrastructure.
 - e. **Administrative expenses directly attributable to the construction, expansion, or modernization (Legal, engineering, permitting fees):** Enter the amount of costs which may include, but is not limited to legal fees, engineering fees, licensing and permitting fees, architecture fees, bond fees, safety and environmental protection costs, costs associated with receiving CHIPS funding, inspection fees, insurance costs, capitalized interest, and other related expenses.
 - f. **Other Capital Investment:** Enter the amount of costs which may include other costs not mentioned above and should be detailed in the schedule.

2. **Operating Losses and other cash outflows until project cash flows breakeven:** Enter the amount of estimated operating losses/cash outflows, including upgrade investments, maintenance, interest expenses, and working capital once the project is operationalized until cash flow breakeven.
3. **Workforce Development Costs:** Enter the spending on workforce development activities to support the proposed project.
4. **Other Uses of Funds:** Provide any uses of funds during the construction phase of the project and until cash flows turn positive, beyond the capital investments, operating losses and other cash outflows, and workforce development costs.

Total Project Costs: Ensure the Total Project Costs for the project equal the sum of line items 1 – 4 in the Use of Funds Form. Total Project Funding in Schedule B must match the Total Project Costs in Schedule A.

3.ii. Sources of Funds Form

Instructions: Complete the fields under the Schedule B: Summation Across Projects – Sources Schedule (\$ USD) section under the Sources of Funds Form with cost estimates. This section should include estimates for all sources of funding that will contribute to the project.

Note, total project funding must fall below \$300 million. Full Applications determined to be ineligible, incomplete, or nonresponsive will be rejected. Potential applicants should enter “0” for any sources that are not applicable to their project.

Schedule B: Summation Across Projects – Sources Schedule (\$ USD)

Please enter the amounts for the following categories (units should not be in Thousands or Millions).

1. **Equity Funding:** Include Sponsor Equity (i.e., applicant, intermediate entity, and/or corporate parent equity), Third-Party Equity, and any other forms of equity that is expected to be injected into the project. Please provide a description of the other forms of equity, if entered. Note, this field will automatically sum the fields 1a – 1c below.
 - a. **Sponsor Equity (Applicant and/or Corporate Parent):** Enter the amount of equity that may have been provided directly by the applicant, intermediate entity, and/or corporate parent.
 - b. **Third-Party Equity:** Enter the amount of third-party equity that may have been raised by the applicant legal entity.
 - c. **Other Equity Funding:** Enter the amount of any other forms of equity.
2. **Debt Funding:** Include all debt raised for the project. Do not include debt from CHIPS loans or portions of loans guaranteed by CHIPS program in this section. Note, this field will automatically sum the fields 2a – 2c below.
 - a. **Sponsor Debt:** Enter the amount of intercompany loans that may have been down streamed by the corporate parent to the applicant legal entity or intermediate entity.
 - b. **Third-Party Debt (e.g., Bonds or Loans):** Enter the amount of third-party debt directly raised by the applicant legal entity
 - c. **Other Debt Funding:** Enter the amount of any other forms of debt.

3. **Government Support:** Include any funding received (or expected to be received) by the applicant for the project from Federal, State, and Local governing bodies in the form of direct funding (e.g., grants), debt (e.g., loans, loan guarantees), tax credits, or other forms of incentives (e.g., land awards, subsidized utilities). Incentive amounts are expected to be directionally accurate given industry-normal risks and returns for a project of this nature. Note, this field will automatically sum the fields 3a – 3c below.
 - a. **Anticipated CHIPS Direct Funding Request:** For CHIPS Direct Funding, indicate the amount of direct funding that the entity is requesting. Please ensure this amount equals ONLY 10%, 20% or 30% of capital expenditures (also known as the 1. Capital Investment found in the Cost Schedule)
 - b. **Investment Tax Credit (estimated):** For the Investment Tax Credit, indicate the expected value of the Investment Tax Credit benefit that will act as an additional source of funds for the project. The estimation should take into consideration the initial Investment Tax Credit received on the asset net of the loss of depreciation on the portion of assets receiving the credit (i.e., the portion of the asset earning the Investment Tax Credit cannot be depreciated for future tax benefits). Note that projects eligible for the Advanced Manufacturing Investment Credit (Investment Tax Credit) will not receive an award of more than 20 percent of project capital expenditures.
 - c. **State and Local Government Incentives (Grants + Loans + Tax Credits):** For State and Local Grants, Loans, and Tax Credits, combine the amounts of incentives expected to be received from state governments and local governments for the jurisdictions where the facility will be located. If the approximate amounts of support to be received is known, but the type of incentive is not yet determined (e.g., grant vs. tax credit), then enter the approximate total amount in the “Other State and Local Government Incentives” category.
4. **Other Sources of Funds:** Enter the amount of any other sources of funding. This may include, but is not limited to, equipment financing, sale / leaseback or other real estate financing, and customer funding (e.g., customer pre-payments).

Total Project Funding: Ensure the Total Project Costs for the project is equal to the sum of line items 1 – 4 in the Sources of Funds Form. Total Project Funding in Schedule B must match the Total Project Costs in Schedule A.

If your request for CHIPS funding is 10% of project capital expenditures, the following question will need to be answered.

- **The request for CHIPS funding is 10% of project capital expenditures. Provide your CHIPS incentive justification:** Please use this text box to explain how the financial information submitted for the project supports a conclusion that a CHIPS Direct Funding award will incentivize you to make investments infacility and equipment in the United States that would not occur in the absence of the incentives. If relevant, include other ways that the requested incentives would change the nature, scale, or speed of the investment (maximum 1500 characters).

If your request for CHIPS funding is for 20% or 30% of project capital expenditures, the following question will need to be answered.

- **The request for CHIPS funding is for 20% or 30% of project capital expenditures. Please provide your CHIPS Incentives Justification with a particular focus on (1) how your project advances economic and national security objectives, (2) why the additional funding is**

necessary to make the project commercially viable, and (3) how you intend to fill the funding gap if the Department ultimately issues an award of only 10 percent: Please provide your CHIPS Incentives Justification with a particular focus on (1) how your project advances economic and national security objectives, (2) why the additional funding is necessary to make the project commercially viable, and (3) explain how you intend to fill the funding gap if the Department ultimately issues an award of only 10 percent (maximum 5000 characters)

If your total capital sources do not equal total project costs, the following question will need to be answered.

- **Total project funding should equal total project costs for the full application. Please explain why your total project funding does not equal your total project costs:** Please provide an explanation for the difference. If your total project costs equal your total project funding, you may disregard this step (maximum 5000 characters).

Attestation

You must complete this attestation section of the Full Application before you can access the rest of the Full Application. By completing this section, you acknowledge that:

“Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.”

4. Project Information

4.i. Consortium and Partner Information

Instructions: In the [web portal](#), please populate all applicable and required fields to complete the Full Application Consortium and Partner Information web form. Information that was submitted as part of the Concept Plan may already appear in the relevant fields. You have the option to directly update this information or leave it unchanged, provided that you review it and confirm its accuracy. For more information about consortia and consortium applications, refer to the [Fact Sheet](#) and [FAQs](#) on the CHIPS website and Section I.B.4. of the [Small-Scale Supplier NOFO](#).

Consortium

Please answer the following questions regarding your involvement in a consortium.

- **Is the applicant a part of a consortium?:** Select “Yes” or “No” to indicate whether the applicant is a part of a consortium. A consortium application involves an umbrella entity and multiple participating entities. If the applicant is joining a new consortium in the full application or previously did not apply as a consortium member during in the Concept Plan, please enter information for the consortium title and description.
 - ***If “No” and you are not part of a consortium, the following questions related to consortia are not asked and you may move to the “Partnering Entities, if applicable” section below.***
 - ***If “Yes” and you are a part of a consortium, please answer the following questions.***
 - **Do you have a Consortium Key from the Concept Plan phase?** Select “Yes” or “No” to indicate whether applicant has the Consortium Key generated in their Concept Plan.
 - ***If “Yes” and the applicant has their Consortium Key:*** Please provide the consortium key from the Concept Plan phase.

- **If “No” and the applicant does not have their previous Consortium Key: please complete the following:**
 - **Consortium Title:** Provide a title for the consortium.
 - **Consortium Description:** Provide a description of the consortium.

Partnering Entities, if applicable

Please provide additional information about any other entities you will be partnering with for this project.

- **Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?:** Choose “Yes”, “No”, or “Not determined at this time” from the dropdown menu to indicate whether the applicant anticipates partnering with other entities, both for the construction phase as well as the production phase of the project(s). These could include major customers / suppliers with whom the applicant has partnerships for a particular facility, investors in a project / facility, construction / design partners, and advisors.
 - **Please list each partner and describe their role in the project:** If the answer to the previous question is “Yes”, provide names and brief description of any potential partners (maximum 1500 characters).

4.ii. Project Information

Instructions: In the [web portal](#), please populate all applicable and required fields to complete the Project Information web form. Information that was submitted as part of the Concept Plan may already appear in the relevant fields. You have the option to directly update this information or leave it unchanged, provided that you review it and confirm its accuracy.

Note, if you are the first member of your consortium to apply, a new Consortium Key will be generated and displayed on this page. Please record and share this key with your consortium partners to use in their applications.

- **Site location:** Include the city, state, and zip code for U.S. addresses and equivalent information for foreign addresses. If you do not know the 9-digit zip code for your U.S. location, enter “0000” for the last four digits.

4.iii. Facility Information

Instructions: In the [web portal](#), complete all questions related to the facility that will be included in this application. Information that was submitted as part of the Concept Plan may already appear in the relevant fields. You have the option to directly update this information or leave it unchanged, provided that you review it and confirm its accuracy. A “facility” used in the context of this application refers to a semiconductor materials facility or semiconductor manufacturing equipment facility for which the capital expenditure falls below \$300 million that will be constructed, expanded, or modernized as a result of this project. According to the [Small-Scale Supplier NOFO](#), an application may include a set of capital expenditures for the construction, expansion, or modernization of a single facility.

- **Name:** Provide a name for the facility that corresponds to the way the facility will be referenced in application materials.
- **Project Type:** Choose from “Construction of New Facility” or “Expansion or Modernization of Existing Facility” for the project type for this facility.
- **Facility Type:** Choose from the provided options to indicate the type of this facility. Only one type may be selected per facility submission. Refer to Section I.B.1. in the [Small-Scale Supplier NOFO](#) for details on each of the possible Facility Types that are eligible for this opportunity and see below.
 - **Semiconductor Materials Facilities** for the manufacture or production, including growth or extraction, of materials used to manufacture semiconductors, which are the chemicals, gases, raw and intermediate materials, and other consumables used in semiconductor manufacturing.
 - **Semiconductor Manufacturing Equipment Facilities** for the physical production of specialized equipment integral to the manufacturing of semiconductors and subsystems that enable or are incorporated into the manufacturing equipment.
- **Project Start:** Enter the month and year for the beginning of this facility’s construction activities as they pertain to new construction, expansion, or modernization. If construction has already begun, enter a date in the past.
- **Production Start:** Enter the month and year for when construction activities will be completed and the facility will begin production.
- **Number of Materials / Equipment Produced:** Provide the expected number of materials or equipment produced by the facility. These should match the number of entries that will be inputted in the following section.

Select the “New” button to add a new type of equipment or material that the facility will produce. You can add as many types of equipment or materials as necessary.

- **Enter Equipment Details:**
 - **Equipment Type:** Choose the equipment type being produced at the facility from the options provided. Options include: Deposition, Etching, Lithography, Wafer Slicing, Inspection Systems, Ion Implantation, Diffusion/Oxidation Furnaces, Support Systems, Metrology, Parts (Cleaning/Refurbishment), Materials Handling Facilities, and Other (Provide).
 - **Other Type:** If “Other (Provide)”, provide a description in the space provided.
 - **Peak Monthly Capacity:** Provide an estimated number of units produced monthly when the facility reaches peak production of the equipment for the facility.
 - **Unit of Production:** Provide the unit of production for the equipment.
 - **Cost per Unit of Production:** Provide the cost per unit of production for the equipment.
 - **Projected Price per Unit:** Provide the projected price per unit of production for the equipment.

- **Enter Material Details:**
 - **Material Type:** Choose the material type being produced at the facility from the options provided. Options include: wafers, photoresists, ancillaries, sputtering targets, quantum information systems materials, and Other (Provide).
 - **Other Type:** If “Other (Provide)”, provide a description in the space provided.
 - **Material Details:** Choose the material details from the options provided for the material type being produced at the facility. Options include: Chemicals, Solvents, Metals, and Other (Provide).
 - **Other Description:** If “Other (Provide)”, provide a description in the space provided.
 - **Specific Material:** Provide the name for the specific material being produced at the facility and information about the material.
 - **Peak Monthly Capacity:** Provide an estimated number of units produced monthly when the facility reaches peak production of the material for the facility.
 - **Unit of Production:** Provide the unit of production for the material.
 - **Cost per Unit of Production:** Provide the cost per unit of production for the material.
 - **Projected Price per Unit:** Provide the projected price per unit of production for the material.
 - **Material Uses (Optional):** Provide the specific uses of the material produced at the facility.

Attestation

You must complete this attestation section of the Full Application before you can access the rest of the Full Application. By completing this section, you acknowledge that:

“Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.”

5. Full Application Uploads

5.i. Consortium Narrative

Instructions: For applicants that responded “Yes” to “Is the applicant part of a consortium?” in the Consortium and Partner Information section, they must submit a Consortium Narrative. In the Full Application [web portal](#), submit a PDF attachment that provides (1) a Consortium Narrative of no more than 8 pages indicating confidential pages in accordance with Section IV.H.2. of the [Small-Scale Supplier NOFO](#), and (2) letters of commitment from all entities responsible for executing portions of the proposed scope of work. Please refer to the [Fact Sheet](#) and the Consortium Logistics section in the [FAQs](#) on the CHIPS website and Section 1.B in [Small-Scale Supplier NOFO](#) for more information on consortia.

- **Have there been any changes to your consortium narrative since you submitted the Concept Plan? If there have been no updates, consortium members may simply resubmit the narrative they submitted as part of the concept plan if it also satisfies the requirements for the Full Application:** Select “Yes” or “No” to indicate whether changes have been made to the

consortium narrative since the submission of the Concept Plan.

Overview

A consortium is defined as an association of companies, organizations, and/or governments working together to build vibrant U.S. semiconductor fab clusters. Applicants with projects that support vibrant U.S. clusters are strongly encouraged to apply as consortia to leverage connections with other regional entities. The Department expects that strong consortia will include at least two suppliers, a state or local government entity, and an anchor institution such as a semiconductor fab. Other members may include workforce training providers, labor unions, economic development corporations, institutions of higher education, philanthropic foundations, industry organizations, Tech Hubs, or other relevant entities.

The consortium narrative must detail other members of the consortium and set forth the overall strategic vision of the consortium, among other relevant information as described below. Applicants applying as part of a consortium may work together to satisfy various statutory eligibility and other requirements.

Although consortia are strongly encouraged for cluster-focused applications, the Department still intends to support standalone projects that meaningfully advance any of the three strategic objectives outlined in the Vision for Success.

The consortium narrative must include the following information, and each member is responsible for ensuring consistency across all related applications:

- The individual entities that are members or proposed members of the consortium and the roles of each entity.
- A narrative description of the consortium's overall strategic vision: how that vision aligns with the Department's economic and national security objectives; and the relevance of each proposed project to that vision.
 - Include an explanation of why the proposed projects are necessary to advance the consortium's vision, and why CHIPS funding is necessary to incentivize the relevant investment.
 - For consortia that include a state and/or local government (including quasi-governmental) entity, this narrative should also list any actions that entity is taking or intends to take to facilitate cluster development, such as efforts to coordinate with suppliers on site selection, infrastructure development, workforce development, permitting, and/or community engagement.
- The structure of the consortium, including how members intend to coordinate and/or collaborate with one another.
- **Planned operating model (New for Full Application):** If applicable, any documentation and evidence of the planned operating model, such as the governance structure, decision-making authority/rights, contractual obligations, financial obligations, roles and responsibilities, and any memoranda of understanding.
- **Letters of Commitment (New for Full Application):** Letters of commitment must be attached from all entities responsible for executing portions of the proposed scope of work. For

consortium applicants, this includes letters from other applicants in the consortium confirming their participation in the consortium. Please note that letters of commitment are excluded from the page limit for the Consortium Narrative upload.

5.ii. Full Application Narrative

Instructions: Submit a PDF attachment that provides a Full Application indicating confidential pages in accordance with Section IV.H of the [Small-Scale Supplier NOFO](#). The Full Application should be responsive to the program description (see Section I of the Small-Scale Supplier NOFO) and the Evaluation Criteria (see Section V.C of the Small-Scale Supplier NOFO). Please refer to the [Full Application Fact Sheet](#) and the Full Application section in the [FAQs](#) on the CHIPS website as well as Section IV.H in the [Small-Scale Supplier NOFO](#) and the [Full Application Narrative Guidance](#) for more information on what each of the sections below require. Full Applications are required to contain the following information:

1. Description of Project (no more than 3 pages)
2. Alignment with Economic and National Security Objectives (no more than 10 pages)
3. Commercial Strategy (no more than 3 pages)
4. Financial Information (no more than 5 pages – excluding attachments and appendices)
5. Project Technical Feasibility (no more than 8 pages – excluding attachments and appendices)
6. Workforce and Community Investments (no more than 8 pages – excluding attachments)

In addition to the Full Application narrative, please submit the following required PDF attachments:

- **Environmental Questionnaire:** Please provide one PDF of a completed [Environmental Questionnaire](#).
- **Covered Incentives:** Please provide one PDF of any covered incentive letters, indicating the estimated size and nature of the incentive.
- **Financial Statements:** Please provide one PDF of audited consolidated financial statements at fiscal year-end for each of the last two years, and interim financial statements for the current fiscal year. If the applicant does not have access to audited consolidated financial statements, please upload an explanation for why not.
- **Letters of Commitments from Education and Training Entities:** Please provide one PDF of any letters of commitment from education and training entities and institutions that detail the specific tasks they will perform in support of the applicant's workforce strategy and the resources that will be provided.

5.iii. Addendum to Full Application

Instructions: For returning applicants, please submit a PDF attachment that provides an addendum to the Full Application indicating confidential pages in accordance with Section IV.H of the [Small-Scale Supplier NOFO](#). Only use this section if you have already submitted your Full Application and have been asked to resubmit or include new or additional information to your application. In your addendum upload, please indicate which sections/contents from your original application that you are changing.

5.iv. Supplemental (Optional) Uploads

Instructions: Submit any PDF attachments that provide supplemental information in regard to each of the relevant sections of the Full Application:

- **Consortium Narrative:** Provide one PDF of supplemental documentation for the Consortium Narrative.
- **Full Application Narrative:** Provide one PDF of supplemental documentation for the Full Application Narrative. Optional supplemental documentation for the Full Application Narrative should be included in an appendix, and includes but is not limited to:
 - Any concrete evidence of customer demand, such as off-take agreements, letters of reference or intent, or other pre-purchase commitments.
 - One-page resumes for (a) all key construction management personnel and (b) all key personnel of contractors and any other entities that will play substantial roles in the construction of the project.
 - Community benefits agreements and/or letters of support from community-based organizations and local officials.
 - Inventory of all Federal, state, and local permits, licenses, and approvals required to site, construct, implement, and operate the facility.
 - Economic analyses to support links between proposed community investments, CHIPS Incentives Program goals, and the underlying economic characteristics of a region.
- **Additional Information:** Provide one PDF of general supplemental documentation.

5.v. Financial Model Upload

Instructions: Submit a model which includes a summary of the expected revenues (broken down by number of units sold and price per unit), costs, and cash flows for the project, including key income statement, cash flow statement, and balance sheet information. Applicants should also provide a summary narrative and supporting evidence for key assumptions underlying these projections. Applicants may submit their own financial model but have the option of using the [Financial Model Template](#). Please note that in this link we are providing an updated financial model template compared to the financial model template referenced in the Small-Scale Supplier NOFO. We encourage applicants to use this updated version.

Instructions for how to complete the financial model are located here: [Financial Model Template Instructions](#)

Applicants should provide Microsoft Excel and PDF attachments to the greatest extent feasible to support the information requested in the Financial Information section. In particular, the financial statements, and project cash flows should be in the format of a dynamic, integrated spreadsheet in Microsoft Excel. The program should permit variable inputs to the key assumptions and clearly identify key inputs and assumptions in the model. Applicant and project-level financials should be prepared in accordance with Generally Accepted Accounting Principles or comparable standards (e.g., International Financial Reporting Standards). The income statement, balance sheet, and statement of cash flows should also be linked together.

5.vi. Standard Forms (Optional)

Instructions: Submit any PDF attachments of the standard forms listed below:

- [SF-328, Certificate Pertaining to Foreign Interests](#)
- [CD-511, Certification Regarding Lobbying](#)
 - Please enter “2023-NIST-CHIPS-CRDF-01” in the Award Number Field and the title of the application, or an abbreviation of that title, in the Project Name field. The link to form can be found here:
- [SF-LLL, Disclosure of Lobbying Activities](#) (Only if applicable)

6. Eligibility Questions

Instructions: In the [web portal](#), you must complete the eligibility section of the Full Application. If you have answered a question in your narrative uploads, provide reference to the document(s), section(s), and page number(s) in your answer here. If applying as part of a consortium with other applicants, you may work together to satisfy various statutory eligibility and other requirements.

The statutory requirements are described below and in the [Small-Scale Supplier NOFO](#) and are put into place to ensure taxpayer funds are used appropriately, support a skilled and diverse US workforce, drive economic opportunity and inclusive economic growth, fortify US national security, and strengthen supply chain resilience.

- **Describe how you are a “covered entity”:** A covered entity means a nonprofit entity, a private entity, a consortium of private entities, or a consortium of nonprofit, public, and private entities with a demonstrated ability to substantially finance, construct, expand, or modernize a facility relating to materials used to manufacture semiconductors or semiconductor manufacturing equipment.
- **Describe how you satisfy each of these requirements: (See below)**
 - Do you have a documented interest in constructing, expanding, or modernizing an eligible facility?
 - Have you been offered a covered incentive from a state or local jurisdiction?
 - Have you made commitments to worker and community investment, including through training and education benefits and programs to expand employment opportunity for economically disadvantaged individuals?
 - Have you secured commitments from regional education and training entities and institutions of higher education to provide workforce training, including programming for training and job placement of economically disadvantaged individuals?
 - Do you have an executable plan to sustain the facility without additional funding from the CHIPS incentives Program?
 - Have you documented your workforce needs and produced a strategy to meet such workforce needs?
 - Have you determined the types of semiconductor technology you will produce at the proposed facility, and the customers, or categories of customers, to whom the items will be sold?

- Do you have an executable plan to identify and mitigate relevant semiconductor supply chain security risks, such as risks associated with access, availability, confidentiality, integrity, and a lack of geographic diversification in your supply chain?

7. Attestation and Submission

Instructions: In the [web portal](#), you must complete the attestation and certifications before you can submit the Full Application. By completing this section and submitting the Full Application you acknowledge the following statements.

The CHIPS Program Office (CPO) recognizes the importance of protecting confidential business information and will follow all applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C. of the [Small-Scale Supplier NOFO](#) for a further discussion of these laws.

Submission Certifications:

- ☐ The individual submitting the Application certifies on behalf of the applicant entity that the applicant information and data submitted and the representations made in the Application are true, complete and accurate, to the best of the applicant's knowledge and belief after due inquiry
- ☐ The individual submitting the Application certifies on behalf of the applicant that the applicant understands that CPO and the Department of Commerce will rely on the accuracy and completeness of the applicant information and data submitted and the representations made in the Application and that any false, fictitious or fraudulent statement or representation made in the Application may be the basis for rejection of the Application or subject the applicant to criminal, civil, or administrative penalties pursuant to 18 U.S.C. 1001.
- ☐ The individual submitting the Application certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the Application may be accessed and used by federal employees, consultants and contractors in accordance with the [Small-Scale Supplier NOFO](#), Section IV.C. (Confidential Information).
- ☐ The individual submitting the Application certifies that they possess the full legal power and authority to submit the Application and make the preceding certifications on behalf of the applicant.
- ☐ The individual submitting the Application agrees that neither the applicant entity nor any of its affiliates may issue any press release or otherwise publicly disclose the status of the Application or the contents of any communications with CPO or the Department of Commerce without CPO's prior written consent.
- ☐ The individual submitting the Full Application certifies that they possess the full legal power and authority to bind the applicant.